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N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

| V _{(BR)DSS} | R _{DS(ON)} | I _D T _A = +25°C |
|----------------------|------------------------------|--|
| 100V | 6.0Ω @ V _{GS} = 10V | 170mA |

Description

This MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Small Servo Motor Control
- Power MOSFET Gate Drivers
- Switching Applications

Features and Benefits

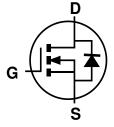
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- High Drain-Source Voltage Rating
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Mechanical Data

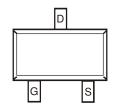
- Case: SOT323
- Case Material: Molded Plastic, "Green" Molding Compound, UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Matte Tin Finish annealed over Alloy 42 Leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
 Weight: 0.006 grams (approximate)







Equivalent Circuit



Top View

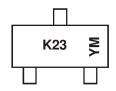
Ordering Information (Notes 4 & 5)

| Part Number | Compliance | Case | Packaging |
|--------------|------------|--------|------------------|
| BSS123WQ-7-F | Automotive | SOT323 | 3000/Tape & Reel |

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product_grade_definitions/.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html

Marking Information



K23 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: B = 2014) M = Month (ex: 9 = September)

Date Code Key

| 2410 0040 | | | | | | | | | | | | | | |
|-----------|------|------|------|------|------|-----|------|------|------|------|------|------|------|------|
| Year | 2002 | 2003 | 2004 | 2005 | 2006 | | 2014 | 2015 | 2016 | 2017 | 2018 | 2019 | 2020 | 2021 |
| Code | N | Р | R | S | Т | | В | С | D | Е | F | G | Н | I |
| Month | Jan | Feb | Ma | ar | Apr | May | Jun | Jul | Aug | Se | р | Oct | Nov | Dec |
| Code | 1 | 2 | 9 | ₹ . | 4 | 5 | 6 | 7 | 8 | 9 | | 0 | N | D |



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

| Characteri | stic | Symbol | Value | Units |
|--|----------------------|-----------------------------------|------------|-------|
| Drain-Source Voltage | | V _{DSS} | 100 | V |
| Drain-Gate Voltage $R_{GS} \le 20 K\Omega$ | | V_{DGR} | 100 | V |
| Gate-Source Voltage | Continuous | V _{GSS} | ±20 | V |
| Drain Current (Note 6) | Continuous Pulsed | I _D I _{DM} | 170 680 | mA |

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Units |
|--|-----------------------------------|-------------|-------|
| Total Power Dissipation (Note 6) | P_{D} | 200 | mW |
| Thermal Resistance, Junction to Ambient (Note 6) | $R_{\theta JA}$ | 625 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55 to +150 | °C |

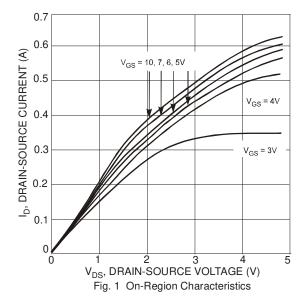
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

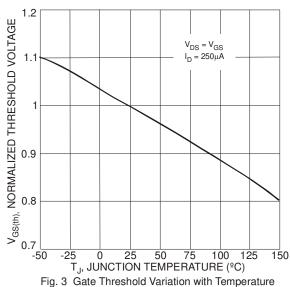
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition |
|------------------------------------|---------------------|-----|------|-----------|----------|---|
| OFF CHARACTERISTICS (Note 7) | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 100 | _ | | V | $V_{GS} = 0V, I_D = 250\mu A$ |
| Zero Gate Voltage Drain Current | I _{DSS} | _ | | 1.0 10 | μA nA | $V_{DS} = 100V, V_{GS} = 0V$ $V_{DS} = 20V, V_{GS} = 0V$ |
| Gate-Body Leakage, Forward | I _{GSSF} | _ | _ | 50 | nA | V _{GS} = 20V, V _{DS} = 0V |
| ON CHARACTERISTICS (Note 7) | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | 0.8 | 1.4 | 2.0 | V | $V_{DS} = V_{GS}, I_D = 1mA$ |
| Static Drain-Source On-Resistance | R _{DS(ON)} | _ | | 6.0 10 | Ω | $V_{GS} = 10V, I_D = 0.17A$ $V_{GS} = 4.5V, I_D = 0.17A$ |
| Forward Transconductance | g _{FS} | 80 | 370 | _ | mS | V _{DS} = 10V, I _D = 0.17A, f = 1.0KHz |
| Drain-Source Diode Forward Voltage | V _{SD} | _ | 0.84 | 1.3 | V | V _{GS} = 0V, I _S = 0.34A |
| DYNAMIC CHARACTERISTICS (Note 8) | • | | | | | |
| Input Capacitance | Ciss | _ | 29 | 60 | pF | |
| Output Capacitance | Coss | _ | 10 | 15 | pF | $V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz$ |
| Reverse Transfer Capacitance | C _{rss} | _ | 2 | 6 | pF | |
| SWITCHING CHARACTERISTICS(Note 8) | | | | | | |
| Turn-On Rise Time | tr | _ | | 8 | ns | |
| Turn-Off Fall Time | | _ | | 16 | ns | $V_{DD} = 30V, I_D = 0.28A,$ |
| Turn-On Delay Time | t _{D(ON)} | _ | | 8 | ns | $R_{GEN} = 6.0\Omega$, $V_{GS} = 10V$ |
| Turn-Off Delay Time | t _{D(OFF)} | _ | _ | 13 | ns | |

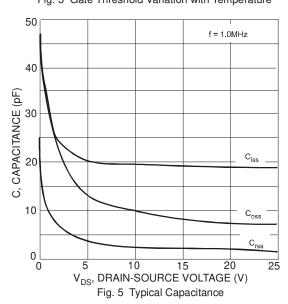
Notes:

- 6. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at http://www.diodes.com.
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to production testing.









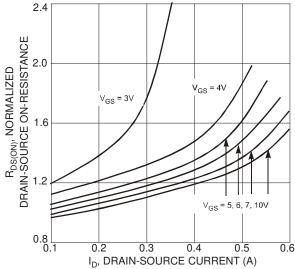


Fig. 2 On-Resistance Variation with Gate Voltage and Drain-Source Current

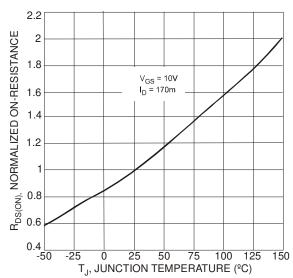
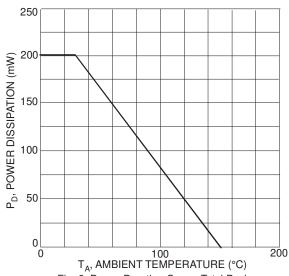


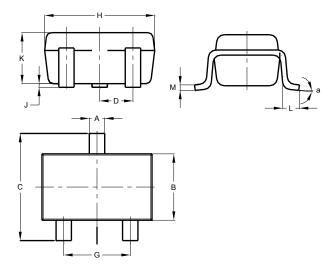
Fig. 4 On-Resistance Variation with Temperature





Package Outline Dimensions

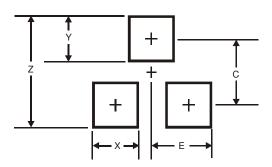
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



| SOT323 | | | | | | | |
|----------------------|-------|---------|-------|--|--|--|--|
| Dim | Min | Max | Тур | | | | |
| Α | 0.25 | 0.40 | 0.30 | | | | |
| В | 1.15 | 1.35 | 1.30 | | | | |
| С | 2.00 | 2.20 | 2.10 | | | | |
| D | 0. | .650 BS | С | | | | |
| F | 0.375 | 0.475 | 0.425 | | | | |
| G | 1.20 | 1.40 | 1.30 | | | | |
| Н | 1.80 | 2.20 | 2.15 | | | | |
| J | 0.00 | 0.10 | 0.05 | | | | |
| K | 0.90 | 1.00 | 0.95 | | | | |
| L | 0.25 | 0.40 | 0.30 | | | | |
| M | 0.10 | 0.18 | 0.11 | | | | |
| а | 8°C | | | | | | |
| All Dimensions in mm | | | | | | | |

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| Z | 2.8 |
| X | 0.7 |
| Y | 0.9 |
| С | 1.9 |
| E | 1.0 |



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